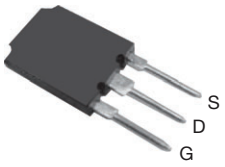
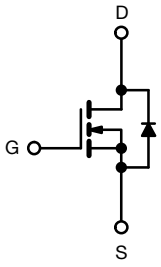
Power MOSFET

SUPER-247





N-Channel MOSFET

FEATURES

- Low figure-of-merit R_{on} x Q_g
- 100 % avalanche tested
- High peak current capability
- dv/dt ruggedness
- Improved t_{rr}/Q_{rr}
- Improved gate charge
- High power dissipations capability
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

PRODUCT SUMMARY		
V_{DS} (V) at T_J max.	560	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	0.270
Q_g max. (nC)	76	
Q_{gs} (nC)	21	
Q_{gd} (nC)	34	
Configuration	Single	

ORDERING INFORMATION	
Package	Super-247
Lead (Pb)-free	SiHS20N50C-E3

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	500	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain current (T_J = 150 °C) [a]	V_{GS} at 10 V	T_C = 25 °C	I_D	20	A
		T_C = 100 °C		11	
Pulsed drain current [b]			I_{DM}	80	
Linear derating factor				1.8	W/°C
Single pulse avalanche energy [c]			E_{AS}	361	mJ
Maximum power dissipation			P_D	250	W
Reverse diode dv/dt [d]			dv/dt	5	V/ns
Operating junction and storage temperature range			T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) [d]	For 10 s			300	

Notes

a. Limited by maximum junction temperature
b. Repetitive rating; pulse width limited by maximum junction temperature
c. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.5 mH, R_g = 25 Ω, I_{AS} = 17 A
d. $I_{SD} \leq$ 18 A, di/dt ≤ 380 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 150 °C
e. 1.6 mm from case

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	40	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	0.5	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	500	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA	-	0.7	-	V/°C
Gate-source threshold voltage (N)	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	3.0	-	5.0	V
Gate-source leakage	I_{GSS}	V_{GS} = ± 30 V	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 500 V, V_{GS} = 0 V	-	-	25	µA
		V_{DS} = 400 V, V_{GS} = 0 V, T_J = 125 °C	-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 10 A	-	0.225	0.270	Ω
Forward transconductance	g_{fs}	V_{DS} = 50 V, I_D = 10 A	-	6.4	-	S
Dynamic						
Input capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	-	2451	2942	pF
Output capacitance	C_{oss}		-	300	360	
Reverse transfer capacitance	C_{rss}		-	26	32	
Total gate charge	Q_g	V_{GS} = 10 V, I_D = 18 A, V_{DS} = 400 V	-	65	76	nC
Gate-source charge	Q_{gs}		-	21	-	
Gate-drain charge	Q_{gd}		-	29	-	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 250 V, I_D = 18 A, R_g = 9.1 Ω	-	80	-	ns
Rise time	t_r		-	27	-	
Turn-off delay time	$t_{d(off)}$		-	32	-	
Fall time	t_f		-	44	-	
Gate input resistance	R_g	f = 1 MHz, open drain	-	1.1	-	Ω
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	20	A
Pulsed diode forward current	I_{SM}		-	-	80	
Diode forward voltage	V_{SD}	T_J = 25 °C, I_S = 18 A, V_{GS} = 0 V	-	-	1.5	V
Reverse recovery time	t_{rr}	T_J = 25 °C, I_F = I_S, di/dt = 100 A/µs, V_R = 35 V	-	503	-	ns
Reverse recovery charge	Q_{rr}		-	6.7	-	µC
Reverse recovery current	I_{RRM}		-	30	-	A

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

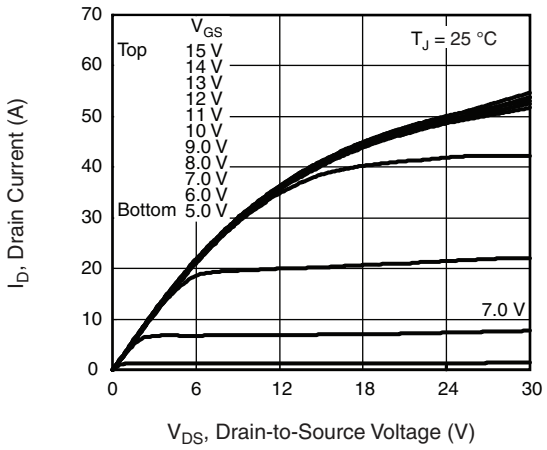


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

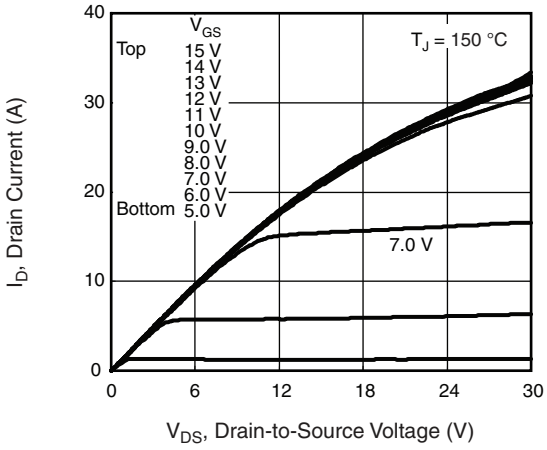


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

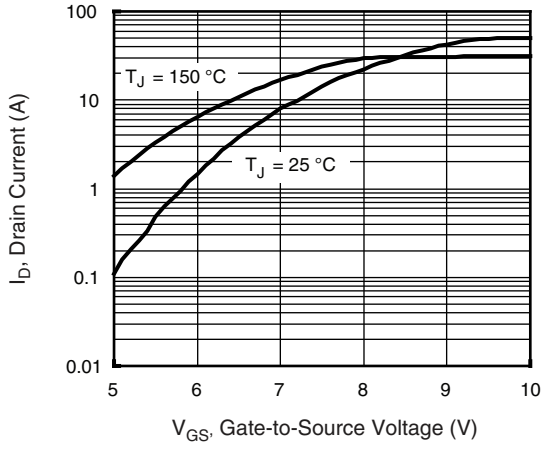


Fig. 3 - Typical Transfer Characteristics

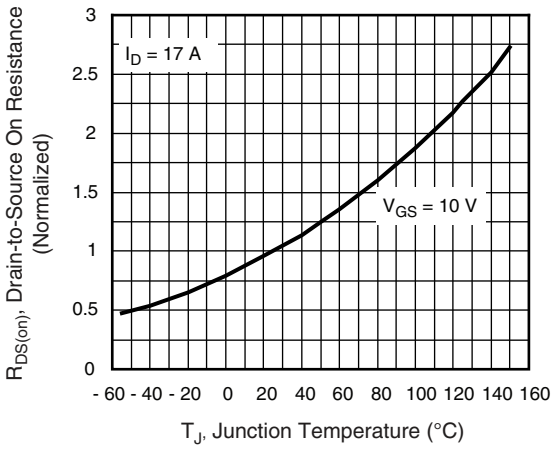


Fig. 4 - Normalized On-Resistance vs. Temperature

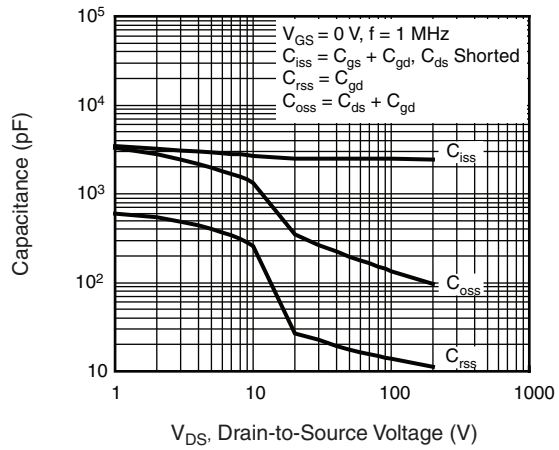


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

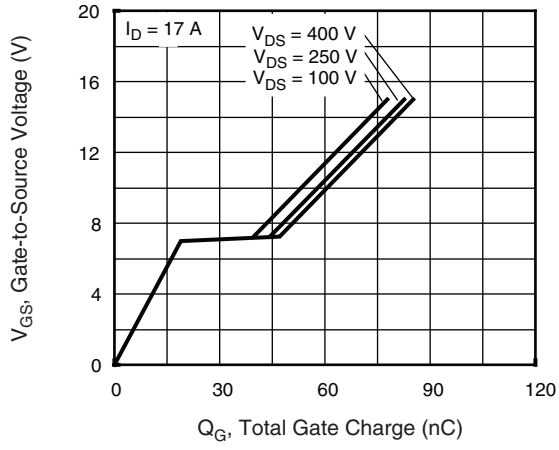


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

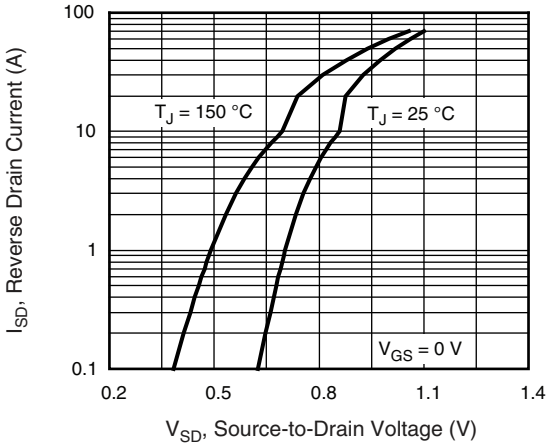


Fig. 7 - Typical Source-Drain Diode Forward Voltage

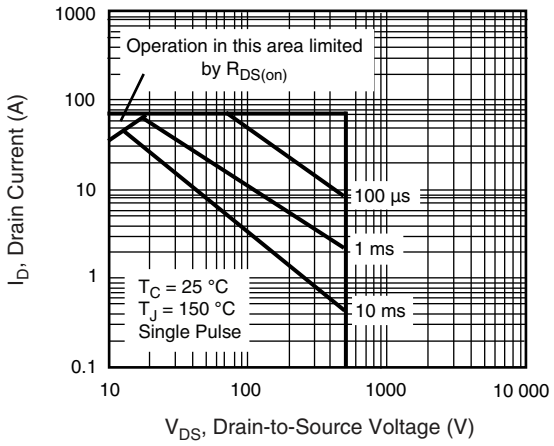


Fig. 8 - Maximum Safe Operating Area

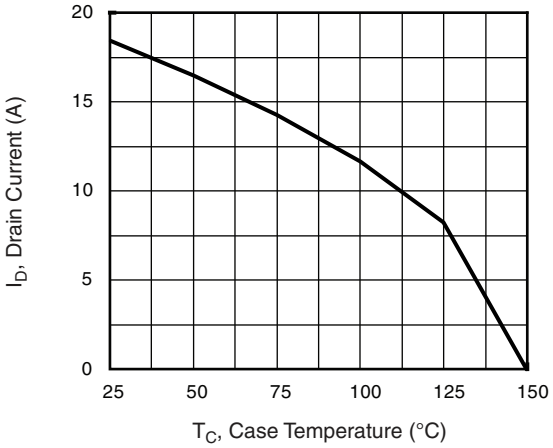


Fig. 9 - Maximum Drain Current vs. Case Temperature

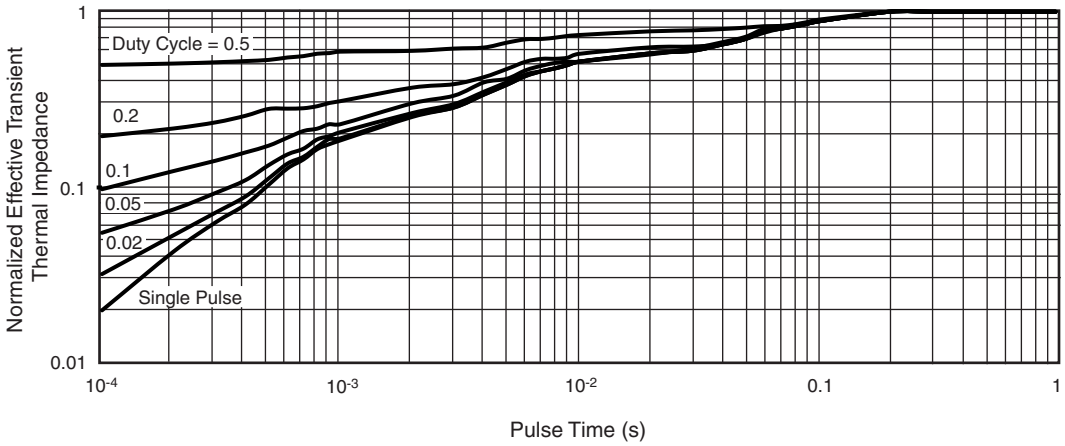


Fig. 10 - Normalized Thermal Transient Impedance, Junction-to-Case (Super-247)

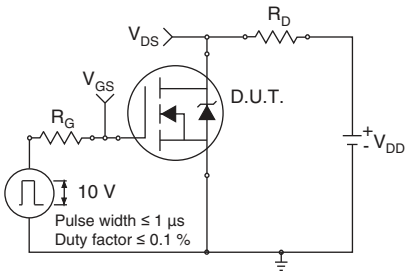


Fig. 11 - Switching Time Test Circuit

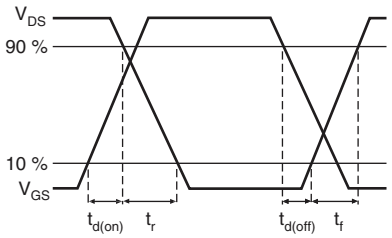


Fig. 12 - Switching Time Waveforms

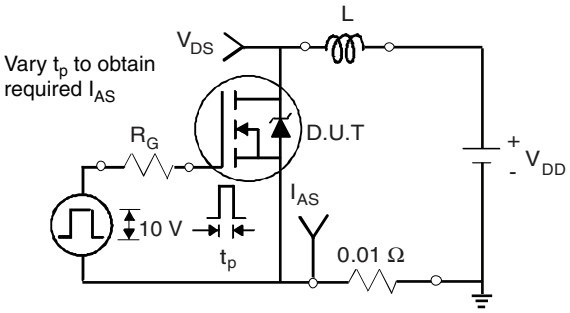


Fig. 13 - Unclamped Inductive Test Circuit

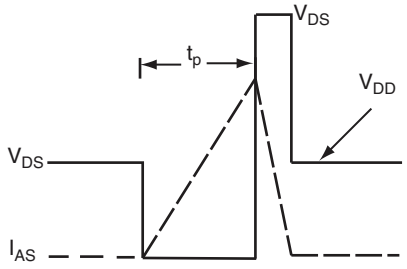


Fig. 14 - Unclamped Inductive Waveforms

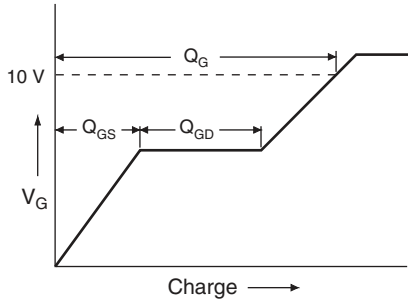


Fig. 15 - Basic Gate Charge Waveform

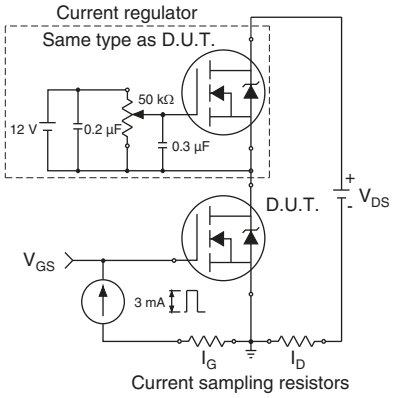
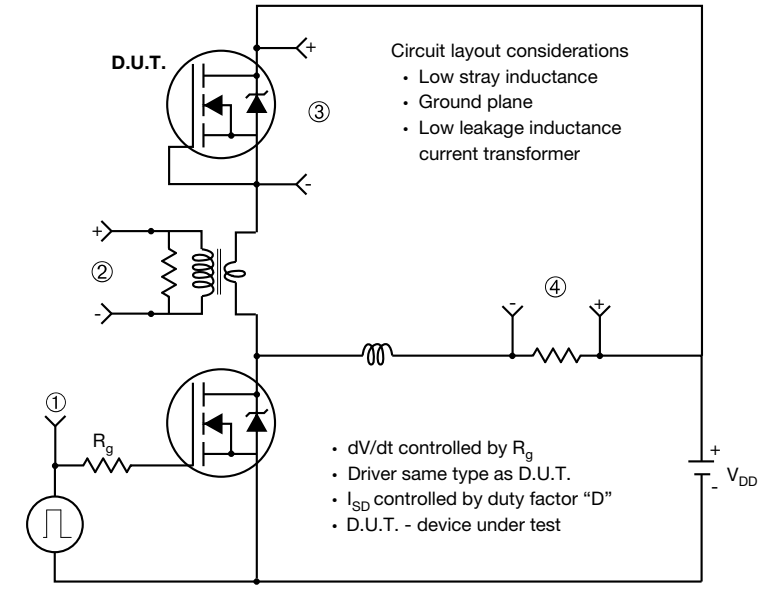
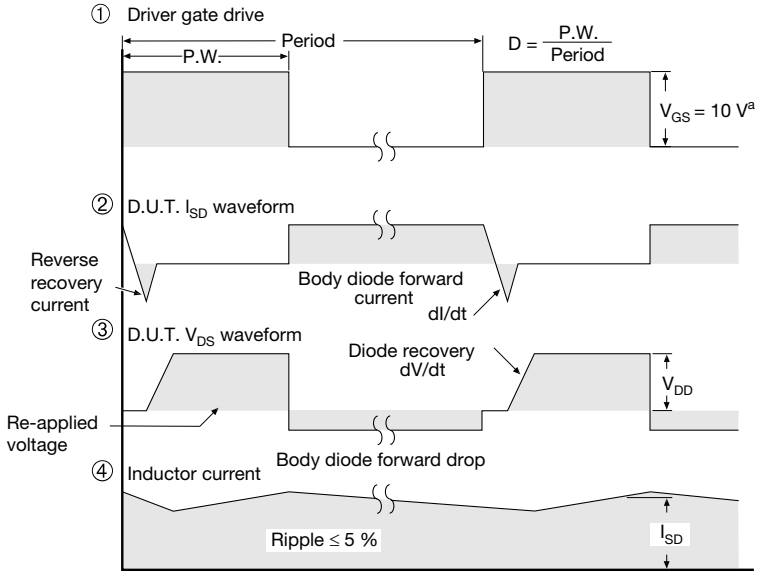


Fig. 16 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit





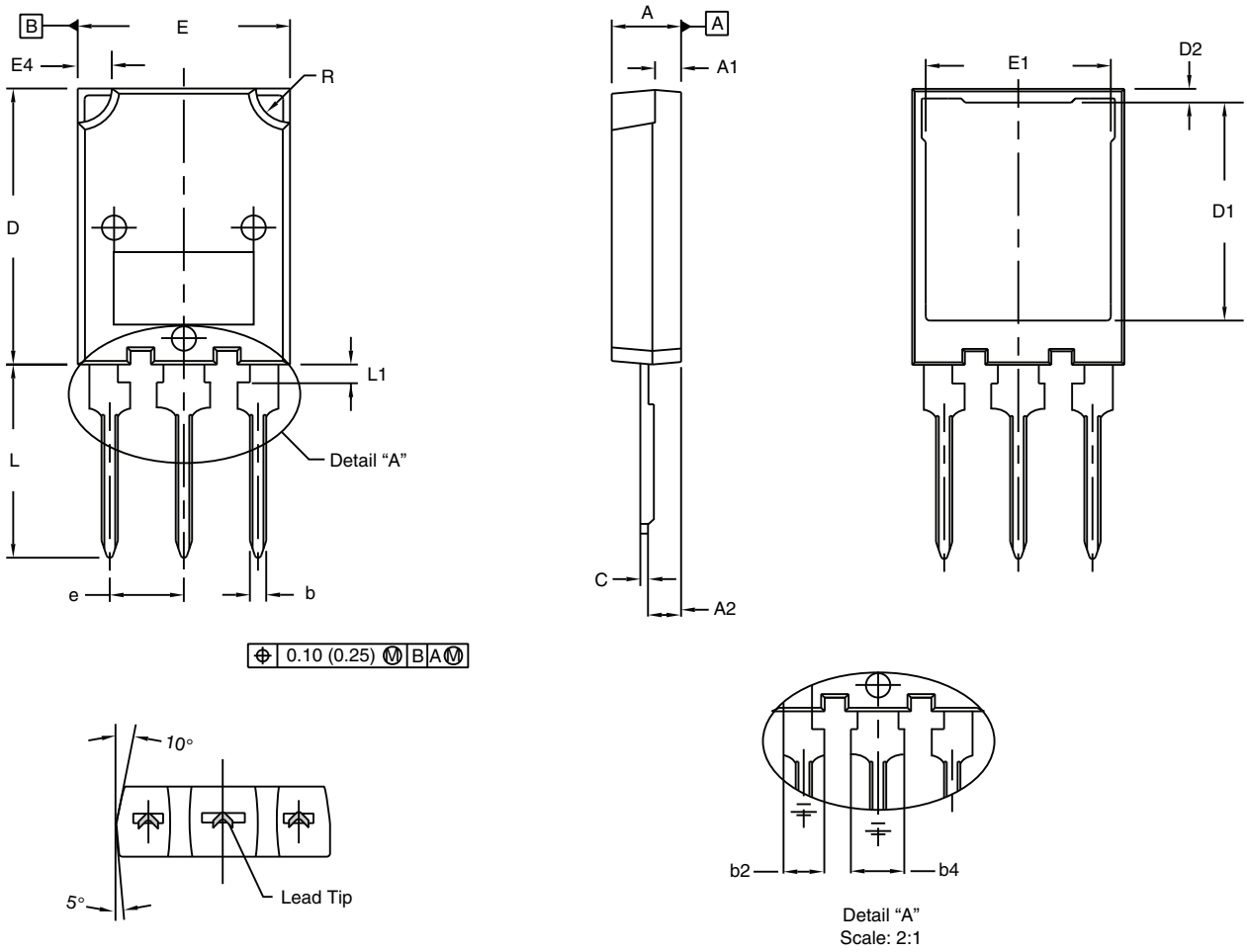
Note

a. V_{GS} = 5 V for logic level devices

Fig. 17 - For N-Channel

TO-274AA (High Voltage)

VERSION 1: FACILITY CODE = Y



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.70	5.30	0.185	0.209
A1	1.50	2.50	0.059	0.098
A2	2.25	2.65	0.089	0.104
b	1.30	1.60	0.051	0.063
b2	1.80	2.20	0.071	0.087
b4	3.00	3.25	0.118	0.128
c (1)	0.38	0.89	0.015	0.035
D	19.80	20.80	0.780	0.819

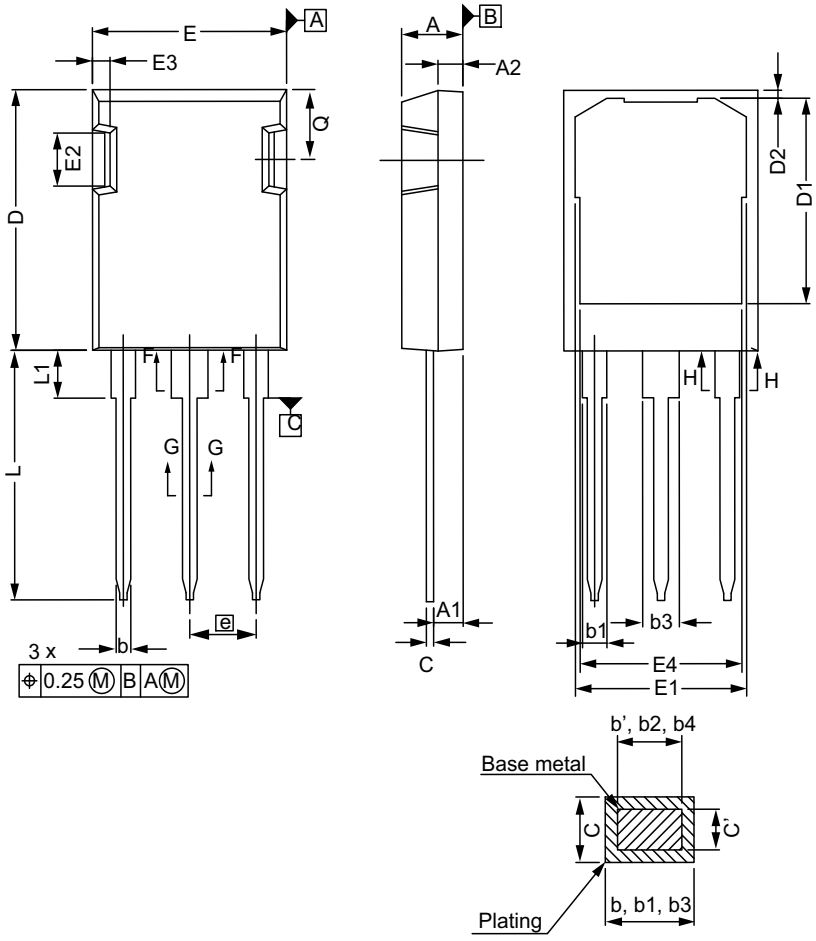
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	15.50	16.10	0.610	0.634
D2	0.70	1.30	0.028	0.051
E	15.10	16.10	0.594	0.634
E1	13.30	13.90	0.524	0.547
e	5.45 BSC		0.215 BSC	
L	13.70	14.70	0.539	0.579
L1	1.00	1.60	0.039	0.063
R	2.00	3.00	0.079	0.118

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body
- Outline conforms to JEDEC® outline to TO-274AA

(1) Dimension measured at tip of lead

VERSION 2: FACILITY CODE = N



SECTION "F-F", "G-G" AND "H-H"
SCALE: NONE

	MILLIMETERS	
DIM.	MIN.	MAX.
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10

	MILLIMETERS	
DIM.	MIN.	MAX.
D1	16.25	17.65
D2	0.50	0.80
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	3.70	4.00
Q	5.49	6.00

ECN: E20-0538-Rev. C, 19-Oct-2020
DWG: 5975

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Outline conforms to JEDEC® outline to TO-274AD
- Dimensions are measured in mm, angles are in degree
- Metal surfaces are tin plated, except area of cut

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